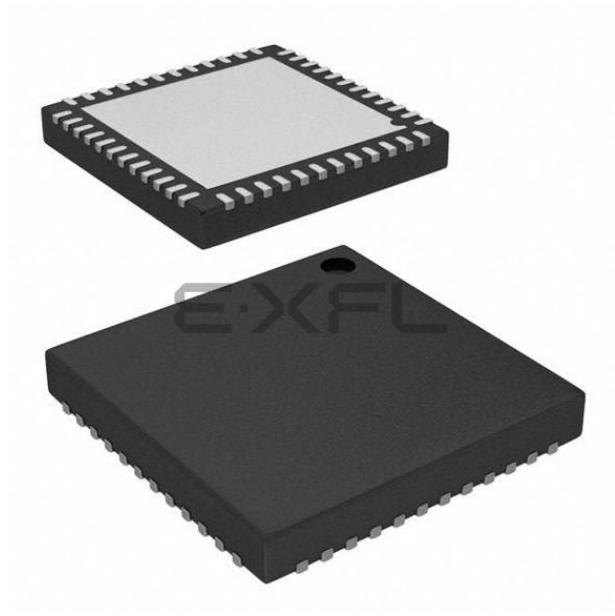
Infineon Technologies - S6E1C12C0AGN20000 Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	CSIO, I²C, LINbus, SmartCard, UART/USART
Peripherals	I²S, LVD, POR, PWM, WDT
Number of I/O	38
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.65V ~ 3.6V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	48-WFQFN Exposed Pad
Supplier Device Package	48-QFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/s6e1c12c0agn20000

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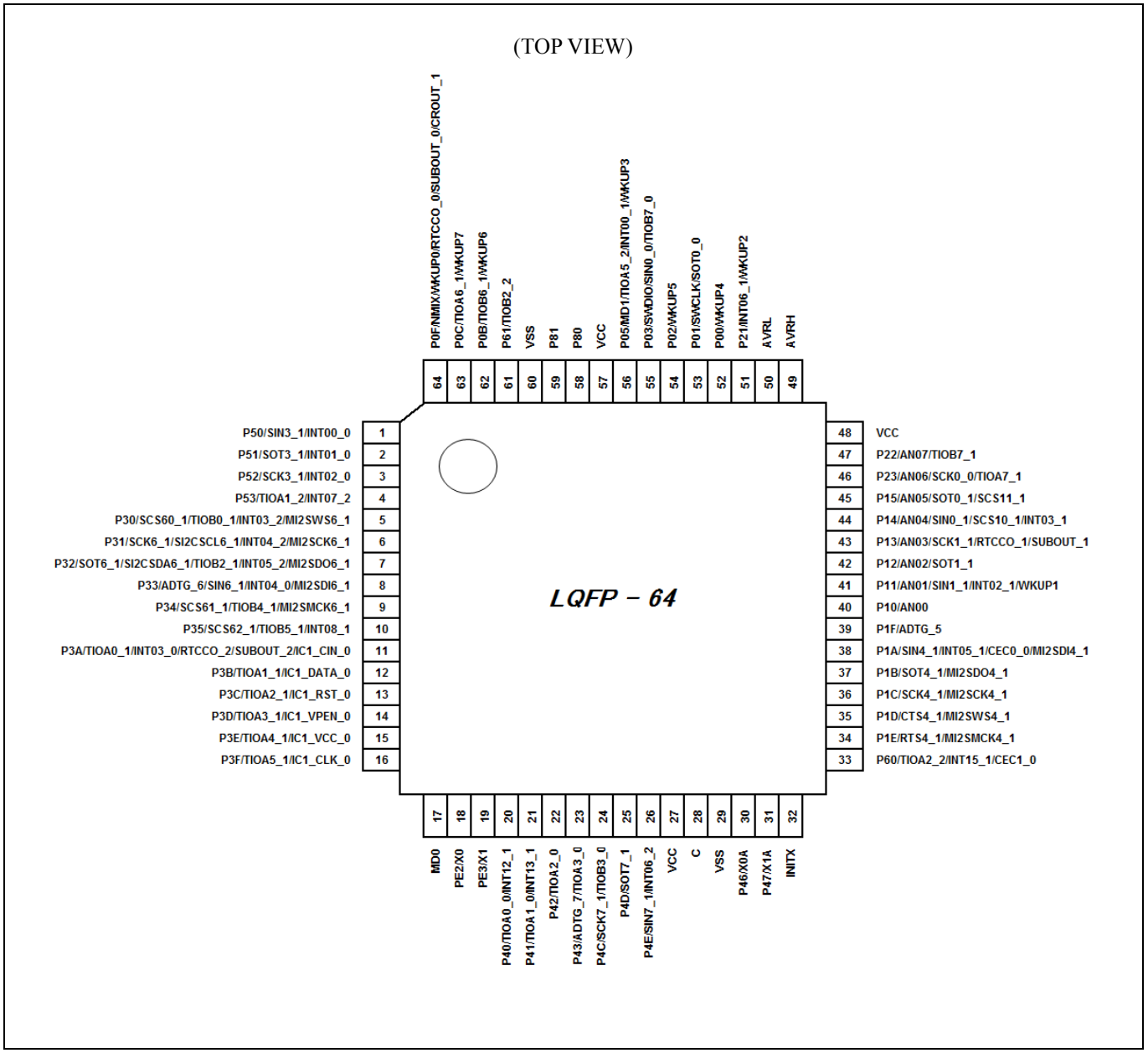
3. Pin Assignment

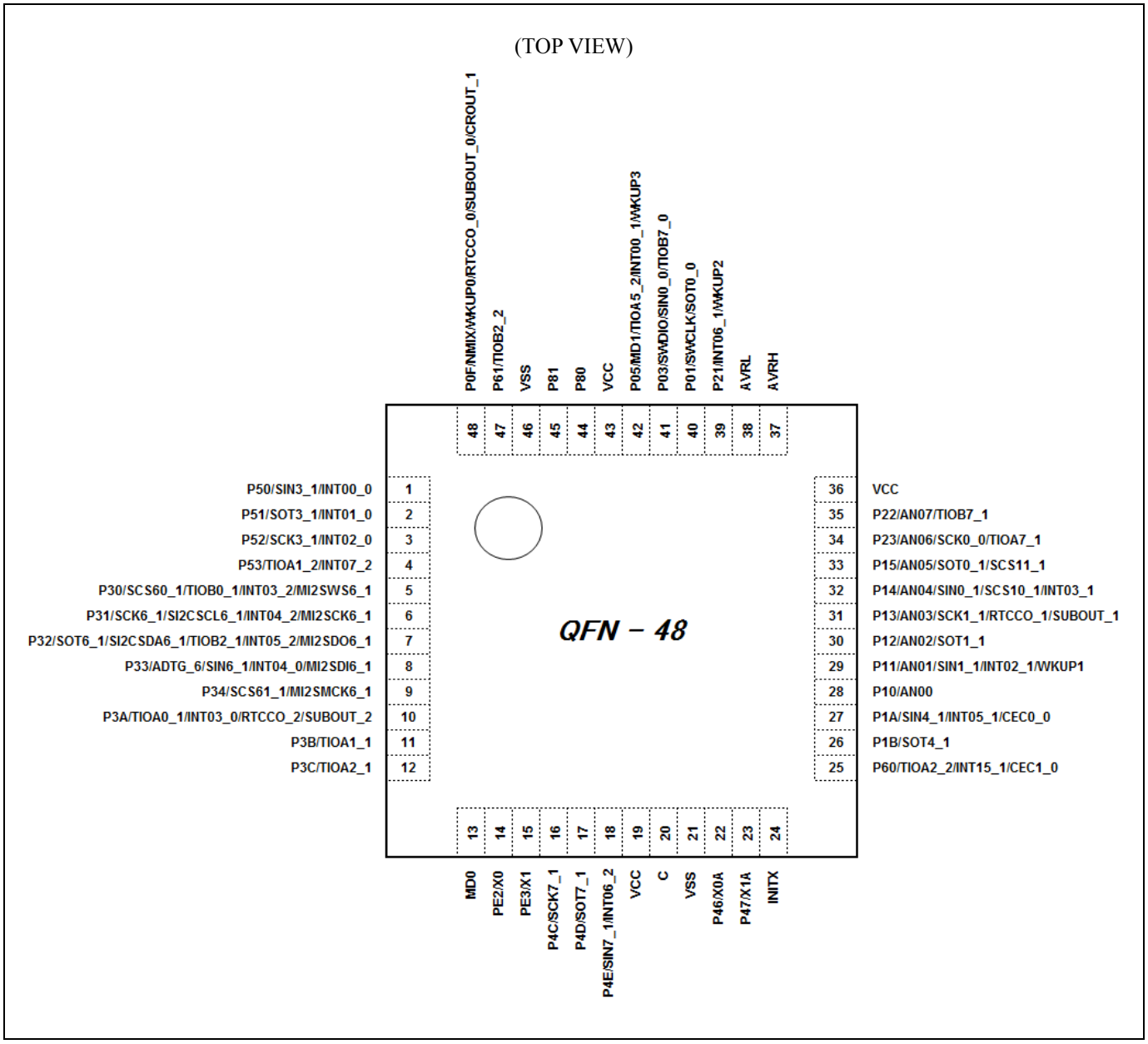
FPT-64P-M38



Note:

- *The number after the underscore ("_") in a pin name such as XXX_1 and XXX_2 indicates the relocated port number. The channel on such pin has multiple functions, each of which has its own pin name. Use the Extended Port Function Register (EPFR) to select the pin to be used.*

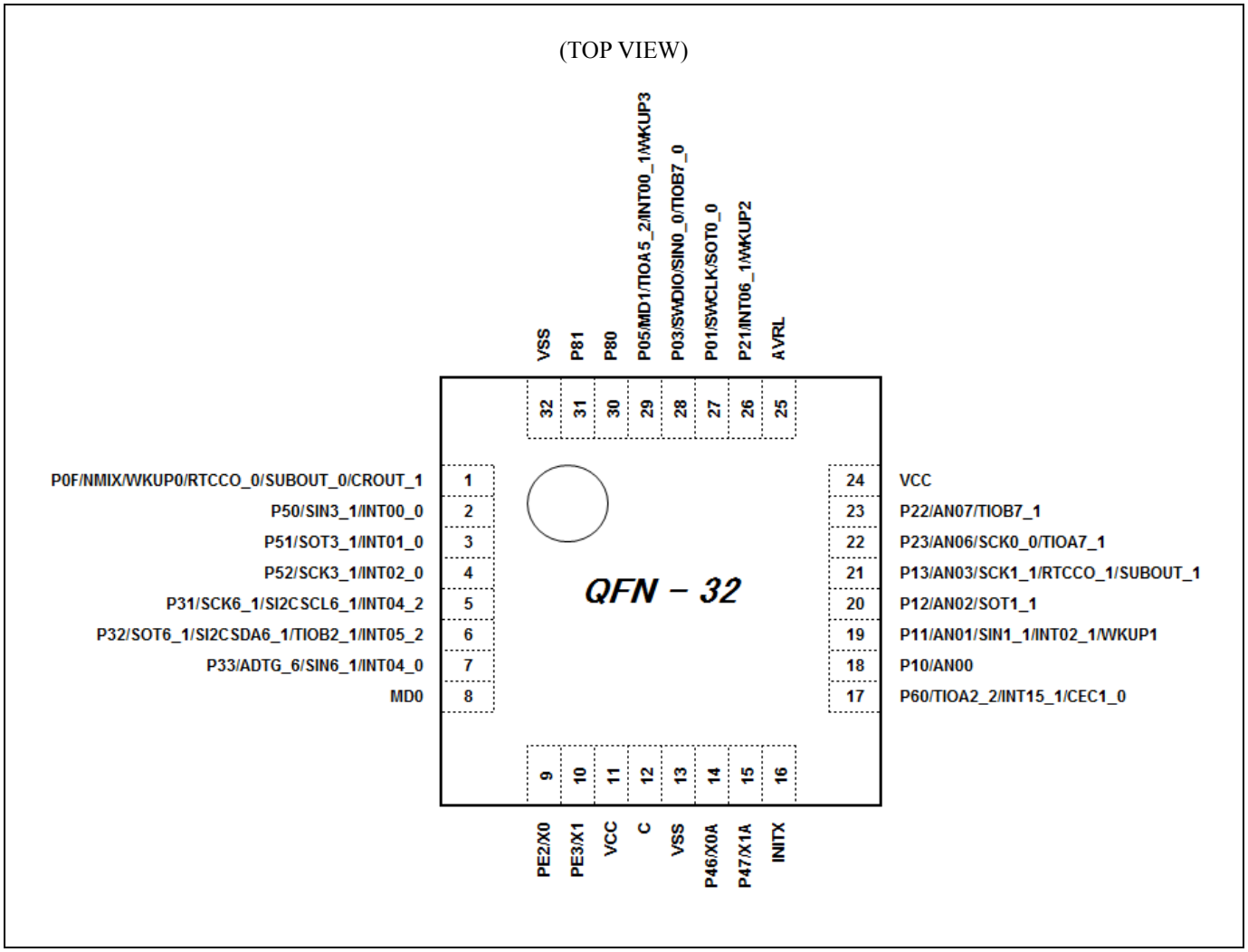
LCC-48P-M74



Note:

- *The number after the underscore ("_") in a pin name such as XXX_1 and XXX_2 indicates the relocated port number. The channel on such pin has multiple functions, each of which has its own pin name. Use the Extended Port Function Register (EPFR) to select the pin to be used.*

LCC-32P-M73



Note:

- *The number after the underscore ("_") in a pin name such as XXX_1 and XXX_2 indicates the relocated port number. The channel on such pin has multiple functions, each of which has its own pin name. Use the Extended Port Function Register (EPFR) to select the pin to be used.*

List of Pin Functions

The number after the underscore ("_") in a pin name such as XXX_1 and XXX_2 indicates the relocated port number. The channel on such pin has multiple functions, each of which has its own pin name. Use the Extended Port Function Register (EPFR) to select the pin to be used.

Pin function	Pin name	Function description	Pin no.		
			LQFP-64 QFN-64	LQFP-48 QFN-48	LQFP-32 QFN-32
ADC	ADTG_5	A/D converter external trigger input pin	39	-	-
	ADTG_6		8	8	7
	ADTG_7		23	-	-
ADC	AN00	A/D converter analog input pin. ANxx describes ADC ch.xx.	40	28	18
	AN01		41	29	19
	AN02		42	30	20
	AN03		43	31	21
	AN04		44	32	-
	AN05		45	33	-
	AN06		46	34	22
	AN07		47	35	23
Base Timer 0	TIOA0_0	Base timer ch.0 TIOA pin	20	-	-
	TIOA0_1		11	10	-
	TIOB0_1	Base timer ch.0 TIOB pin	5	5	-
Base Timer 1	TIOA1_0	Base timer ch.1 TIOA pin	21	-	-
	TIOA1_1		12	11	-
	TIOA1_2		4	4	-
Base Timer 2	TIOA2_0	Base timer ch.2 TIOA pin	22	-	-
	TIOA2_1		13	12	-
	TIOA2_2		33	25	17
	TIOB2_1	Base timer ch.2 TIOB pin	7	7	6
	TIOB2_2		61	47	-
Base Timer 3	TIOA3_0	Base timer ch.3 TIOA pin	23	-	-
	TIOA3_1		14	-	-
	TIOB3_0	Base timer ch.3 TIOB pin	24	-	-
Base Timer 4	TIOA4_1	Base timer ch.4 TIOA pin	15	-	-
	TIOB4_1	Base timer ch.4 TIOB pin	9	-	-
Base Timer 5	TIOA5_1	Base timer ch.5 TIOA pin	16	-	-
	TIOA5_2		56	42	29
	TIOB5_1	Base timer ch.5 TIOB pin	10	-	-
Base Timer 6	TIOA6_1	Base timer ch.6 TIOA pin	63	-	-
	TIOB6_1	Base timer ch.6 TIOB pin	62	-	-
Base Timer 7	TIOA7_1	Base timer ch.7 TIOA pin	46	34	22
	TIOB7_0	Base timer ch.7 TIOB pin	55	41	28
	TIOB7_1		47	35	23
Debugger	SWCLK	Serial wire debug interface clock input pin	53	40	27
	SWDIO	Serial wire debug interface data input / output pin	55	41	28

Pin function	Pin name	Function description	Pin no.		
			LQFP-64 QFN-64	LQFP-48 QFN-48	LQFP-32 QFN-32
Multi-function Serial 1	SIN1_1	Multi-function serial interface ch.1 input pin	41	29	19
	SOT1_1 (SDA1_1)	Multi-function serial interface ch.1 output pin. This pin operates as SOT1 when used as a UART/CSIO/LIN pin (operation mode 0 to 3) and as SDA1 when used as an I2C pin (operation mode 4).	42	30	20
	SCK1_1 (SCL1_1)	Multi-function serial interface ch.1 clock I/O pin. This pin operates as SCK1 when used as a CSIO pin (operation mode 2) and as SCL1 when used as an I2C pin (operation mode 4).	43	31	21
	SCS10_1	Multi-function serial interface ch.1 serial chip select 0 input/output pin.	44	32	-
	SCS11_1	Multi-function serial interface ch.1 serial chip select 1 output pin.	45	33	-
Multi-function Serial 3	SIN3_1	Multi-function serial interface ch.3 input pin	1	1	2
	SOT3_1 (SDA3_1)	Multi-function serial interface ch.3 output pin. This pin operates as SOT3 when used as a UART/CSIO/LIN pin (operation mode 0 to 3) and as SDA3 when used as an I2C pin (operation mode 4).	2	2	3
	SCK3_1 (SCL3_1)	Multi-function serial interface ch.3 clock I/O pin. This pin operates as SCK3 when used as a CSIO (operation mode 2) and as SCL3 when used as an I2C pin (operation mode 4).	3	3	4

11.3 DC Characteristics

11.3.1 Current Rating

Symbol (Pin Name)	Conditions		HCLK Frequency*4	Value Typ*1	Value Max*2	Unit	Remarks
Icc (VCC)	Run mode, code executed from Flash	8 MHz external clock input, PLL ON*8 NOP code executed Built-in high speed CR stopped	8 MHZ	1.4	2.7	mA	*3
			20 MHZ	2.6	4.1		
			40 MHZ	3.9	5.6		
		8 MHz external clock input, PLL ON*8 Benchmark code executed Built-in high speed CR stopped	8 MHZ	1.3	2.6	mA	*3
			20 MHZ	2.3	3.8		
			40 MHZ	3.4	5.1		
		8 MHz crystal oscillation, PLL ON*8 NOP code executed Built-in high speed CR stopped	8 MHZ	1.6	3.0	mA	*3
			20 MHZ	2.8	4.4		
			40 MHZ	4.1	5.9		
	Run mode, code executed from RAM	8 MHz external clock input, PLL ON*8 NOP code executed Built-in high speed CR stopped	8 MHZ	1.0	2.1	mA	*3
			20 MHZ	1.7	2.9		
			40 MHZ	2.7	4.0		
	Run mode, code executed from Flash	8 MHz external clock input, PLL ON NOP code executed Built-in high speed CR stopped PCLK1 stopped	40 MHZ	1.6	3.1	mA	*3,*6,*7
	Run mode, code executed from Flash	Built-in high speed CR*5 NOP code executed All peripheral clock stopped by CKENx	8 MHZ	1.1	2.4	mA	*3
		32 kHz crystal oscillation NOP code executed All peripheral clock stopped by CKENx	32 kHZ	240	1264	µA	*3
		Built-in low speed CR NOP code executed All peripheral clock stopped by CKENx	100 kHZ	246	1271	µA	*3
Iccs (VCC)	Sleep operation	8 MHz external clock input, PLL ON*8 All peripheral clock stopped by CKENx	8 MHZ	0.8	1.9	mA	*3
			20 MHZ	1.3	2.4		
			40 MHZ	1.8	3.0		
		Built-in high speed CR*5 All peripheral clock stopped by CKENx	8 MHZ	0.6	1.7	mA	*3
		32 kHz crystal oscillation All peripheral clock stopped by CKENx	32 kHZ	237	1261	µA	*3
		Built-in low speed CR All peripheral clock stopped by CKENx	100 kHZ	238	1262	µA	*3

*1 : T_A=+25°C,V_{CC}=3.3 V
*2 : T_A=+105°C,V_{CC}=3.6 V
*3 : All ports are fixed
*4 : PCLK0 is set to divided rate 8
*5 : The frequency is set to 8 MHz by trimming
*6 : Flash sync down is set to FRWTR.RWT=111 and FSYNDN.SD=1111
*7 : VCC=1.65 V
*8 : When HCLK=8 MHz, PLL OFF

LVD Current

(V_{CC}=1.65 V to 3.6 V, V_{SS}= 0 V, T_A=- 40°C to +105°C)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Typ	Max		
Low-Voltage detection circuit (LVD) power supply current	I_{CCLVD}	VCC	At operation	0.15	0.3	µA	For occurrence of reset
				0.10	0.3	µA	For occurrence of interrupt

Bipolar Vref Current

(V_{CC}=1.65 V to 3.6 V, V_{SS}= 0 V, T_A=- 40°C to +105°C)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Typ	Max		
Bipolar Vref Current	I_{CCBGR}	VCC	At operation	100	200	µA	

Flash Memory Current

(V_{CC}=1.65 V to 3.6 V, V_{SS}= 0 V, T_A=- 40°C to +105°C)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Typ	Max		
Flash memory write/erase current	$I_{CCFLASH}$	VCC	At Write/Erase	4.4	5.6	mA	

A/D converter Current

(V_{CC}=1.65 V to 3.6 V, V_{SS}= 0 V, T_A=- 40°C to +105°C)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Typ	Max		
Power supply current	I_{CCAD}	VCC	At operation	0.5	0.75	mA	
Reference power supply current (AVRH)	I_{CCAVRH}	AVRH	At operation	0.69	1.3	mA	AVRH=3.6 V
			At stop	0.1	1.3	µA	

11.3.2 Pin Characteristics

(V_{CC} = 1.65 V to 3.6 V, V_{SS}= 0 V, T_A=- 40°C to +105°C)

Parameter	Symbol	Pin Name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
H level input voltage (hysteresis input)	V_{IHS}	CMOS hysteresis input pin, MD0	$V_{CC} \geq 2.7$ V	$V_{CC} \times 0.8$	-	V_{CC} +0.3	V	
			$V_{CC} < 2.7$ V	$V_{CC} \times 0.7$				
		5 V tolerant input pin	$V_{CC} \geq 2.7$ V	$V_{CC} \times 0.8$	-	V_{SS} +5.5	V	
			$V_{CC} < 2.7$ V	$V_{CC} \times 0.7$				
L level input voltage (hysteresis input)	V_{ILS}	CMOS hysteresis input pin, MD0	$V_{CC} \geq 2.7$ V	V_{SS} - 0.3	-	$V_{CC} \times 0.2$	V	
			$V_{CC} < 2.7$ V			$V_{CC} \times 0.3$		
		5 V tolerant input pin	$V_{CC} \geq 2.7$ V	V_{SS} - 0.3	-	$V_{CC} \times 0.2$	V	
			$V_{CC} < 2.7$ V		-	$V_{CC} \times 0.3$		
H level output voltage	V_{OH}	4 mA type	$V_{CC} \geq 2.7$ V, I_{OH} = - 4 mA	V_{CC} - 0.5	-	V_{CC}	V	
			$V_{CC} < 2.7$ V, I_{OH} = - 2 mA	V_{CC} - 0.45				
L level output voltage	V_{OL}	4 mA type	$V_{CC} \geq 2.7$ V, I_{OL} 4 mA	V_{SS}	-	0.4	V	
			$V_{CC} < 2.7$ V, I_{OL}=2 mA					
Input leak current	I_{IL}	-	-	- 5	-	+ 5	µA	
Pull-up resistance value	R_{PU}	Pull-up pin	$V_{CC} \geq 2.7$ V	21	33	48	kΩ	
			$V_{CC} < 2.7$ V	-	-	88		
Input capacitance	C_{IN}	Other than VCC, VSS, AVRH	-	-	5	15	pF	

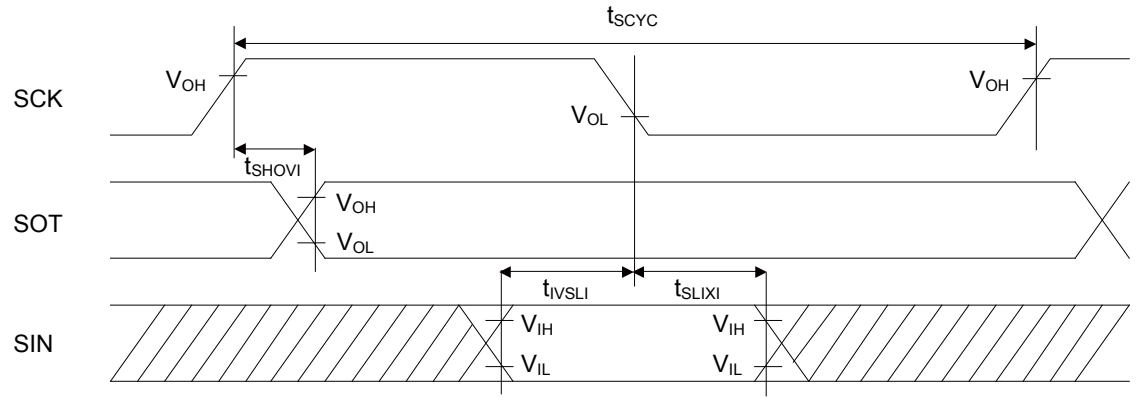
CSIO (SPI=0, SCINV=1)

(V_{CC}= 1.65 V to 3.6 V, V_{SS}= 0 V, T_A=- 40°C to +105°C)

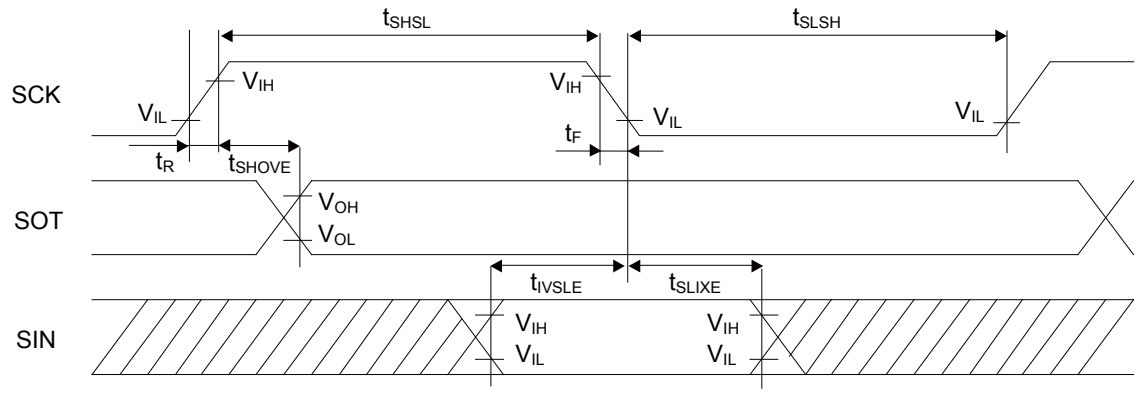
Parameter	Symbol	Pin name	Conditions	V_{CC} < 2.7V		V_{CC} ≥ 2.7V		Unit
				Min	Max	Min	Max	
Serial clock cycle time	t_{SCYC}	SCKx	Master mode	4 t_{CYCP}	-	4 t_{CYCP}	-	ns
SCK ↑ → SOT delay time	t_{SHOVI}	SCKx, SOTx		- 30	+ 30	- 20	+ 20	ns
SIN → SCK ↓ setup time	t_{IVSLI}	SCKx, SINx		50	-	36	-	ns
SCK ↓ → SIN hold time	t_{SLIXI}	SCKx, SINx		0	-	0	-	ns
Serial clock "L" pulse width	t_{SLSH}	SCKx	Slave mode	2 t_{CYCP} - 10	-	2 t_{CYCP} - 10	-	ns
Serial clock "H" pulse width	t_{SHSL}	SCKx		t_{CYCP} + 10	-	t_{CYCP} + 10	-	ns
SCK ↑ → SOT delay time	t_{SHOVE}	SCKx, SOTx		-	50	-	33	ns
SIN → SCK ↓ setup time	t_{IVSLE}	SCKx, SINx		10	-	10	-	ns
SCK ↓ → SIN hold time	t_{SLIXE}	SCKx, SINx		20	-	20	-	ns
SCK falling time	tF	SCKx		-	5	-	5	ns
SCK rising time	tR	SCKx		-	5	-	5	ns

Notes:

- *The above AC characteristics are for clock synchronous mode.*
- *t_{CYCP} represents the APB bus clock cycle time.*
  For the number of the APB bus to which Multi-function Serial has been connected, see "8. Block Diagram".
- *The characteristics are only applicable when the relocate port numbers are the same.*
  For instance, they are not applicable for the combination of SCKx_0 and SOTx_1.
- *External load capacitance C_L=30 pF*



Master mode



Slave mode

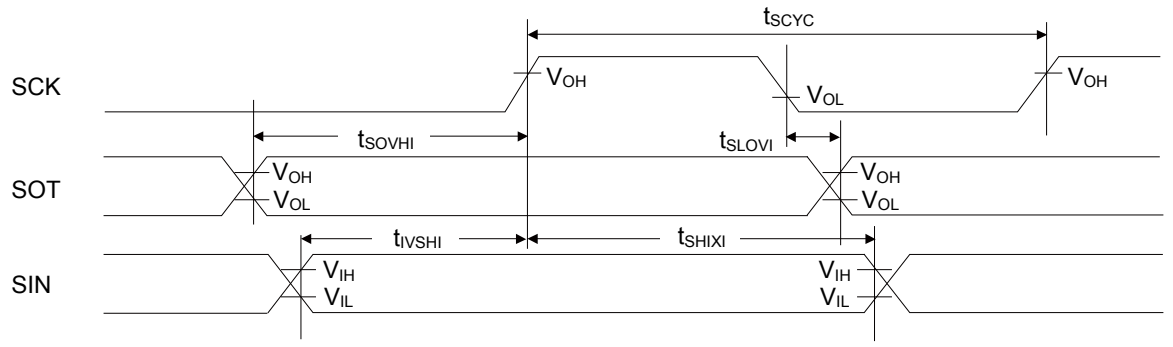
SPI (SPI=1, SCINV=1)

(V_{CC}= 1.65 V to 3.6 V, V_{SS}= 0 V, T_A=- 40°C to +105°C)

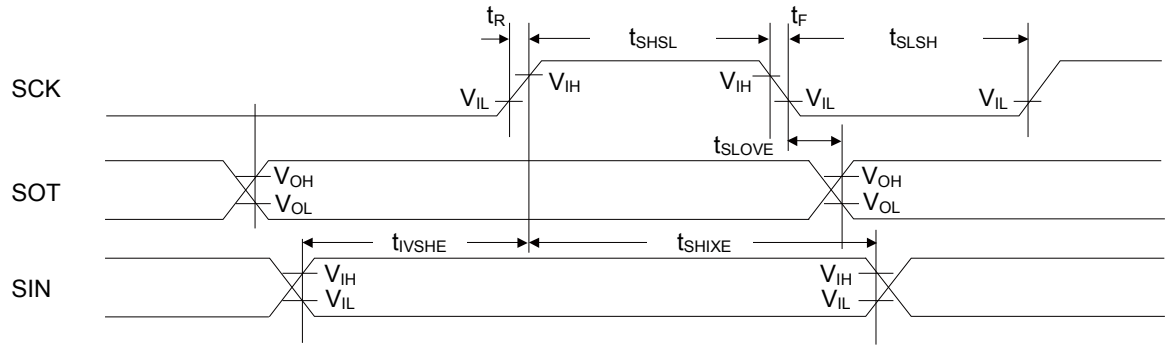
Parameter	Symbol	Pin name	Conditions	V_{CC} < 2.7 V		V_{CC} ≥ 2.7 V		Unit
				Min	Max	Min	Max	
Serial clock cycle time	t_{SCYC}	SCKx	Master mode	4 t_{CYCP}	-	4 t_{CYCP}	-	ns
SCK ↓ → SOT delay time	t_{SLOVI}	SCKx, SOTx		- 30	+ 30	- 20	+ 20	ns
SIN → SCK ↑ setup time	t_{IVSHI}	SCKx, SINx		50	-	36	-	ns
SCK ↑ → SIN hold time	t_{SHIXI}	SCKx, SINx		0	-	0	-	ns
SOT → SCK ↑ delay time	t_{SOVHI}	SCKx, SOTx		2 t_{CYCP} - 30	-	2 t_{CYCP} - 30	-	ns
Serial clock "L" pulse width	t_{SLSH}	SCKx	Slave mode	2 t_{CYCP} - 10	-	2 t_{CYCP} - 10	-	ns
Serial clock "H" pulse width	t_{SHSL}	SCKx		t_{CYCP} + 10	-	t_{CYCP} + 10	-	ns
SCK ↓ → SOT delay time	t_{SLOVE}	SCKx, SOTx		-	50	-	33	ns
SIN → SCK ↑ setup time	t_{IVSHE}	SCKx, SINx		10	-	10	-	ns
SCK ↑ → SIN hold time	t_{SHIXE}	SCKx, SINx		20	-	20	-	ns
SCK falling time	tF	SCKx		-	5	-	5	ns
SCK rising time	tR	SCKx		-	5	-	5	ns

Notes:

- *The above AC characteristics are for clock synchronous mode.*
- *t_{CYCP} represents the APB bus clock cycle time.*
  For the number of the APB bus to which Multi-function Serial has been connected, see "8. Block Diagram".
- *The characteristics are only applicable when the relocate port numbers are the same.*
  For instance, they are not applicable for the combination of SCKx_0 and SOTx_1.
- *External load capacitance C_L=30 pF*



Master mode



Slave mode

When Using CSIO/SPI Chip Select (SCINV=0, CSLVL=1)

(V_{CC}= 1.65 V to 3.6 V, V_{SS}= 0 V, T_A=- 40°C to +105°C)

Parameter	Symbol	Conditions	V_{CC} < 2.7 V		V_{CC} ≥ 2.7 V		Unit
			Min	Max	Min	Max	
SCS↓→SCK↓ setup time	t_{CSSI}	Master mode	(*1)-50	(*1)+0	(*1)-50	(*1)+0	ns
SCK↑→SCS↑ hold time	t_{CSHI}		(*2)+0	(*2)+50	(*2)+0	(*2)+50	ns
SCS deselect time	t_{CSDI}		(*3)-50	(*3)+50	(*3)-50	(*3)+50	ns
SCS↓→SCK↓ setup time	t_{CSSE}	Slave mode	$3t_{CYCP}$+30	-	$3t_{CYCP}$+30	-	ns
SCK↑→SCS↑ hold time	t_{CSHE}		0	-	0	-	ns
SCS deselect time	t_{CSDE}		$3t_{CYCP}$+30	-	$3t_{CYCP}$+30	-	ns
SCS↓→SOT delay time	t_{DSE}		-	55	-	40	ns
SCS↑→SOT delay time	t_{DEE}		0	-	0	-	ns

*1: CSSU bit value × serial chip select timing operating clock cycle.

*2: CSHD bit value × serial chip select timing operating clock cycle.

*3: CSDS bit value × serial chip select timing operating clock cycle.
Irrespective of CSDS bit setting, $5t_{CYCP}$ or more are required for the period the time when the serial chip select pin becomes inactive to the time when the serial chip select pin becomes active again.

Notes:

- *t_{CYCP} indicates the APB bus clock cycle time.*
  For information about the APB bus number which Multi-function Serial is connected to, see "8. Block Diagram".
- *For information about CSSU, CSHD, CSDS, serial chip select timing operating clock, see "FM0+ Family Peripheral Manual".*
- *These characteristics only guarantee the same relocate port number.*
  For example, the combination of SCKx_0 and SCSIx_1 is not guaranteed.
- *When the external load capacitance C_L=30 pF.*

When Using CSIO/SPI Chip Select (SCINV=1, CSLVL=1)

(V_{CC}= 1.65 V to 3.6 V, V_{SS}= 0 V, T_A=- 40°C to +105°C)

Parameter	Symbol	Conditions	V_{CC} < 2.7 V		V_{CC} ≥ 2.7 V		Unit
			Min	Max	Min	Max	
SCS↓→SCK↑ setup time	t_{CSSI}	Master mode	(*1)-50	(*1)+0	(*1)-50	(*1)+0	ns
SCK↓→SCS↑ hold time	t_{CSHI}		(*2)+0	(*2)+50	(*2)+0	(*2)+50	ns
SCS deselect time	t_{CSDI}		(*3)-50	(*3)+50	(*3)-50	(*3)+50	ns
SCS↓→SCK↑ setup time	t_{CSSE}	Slave mode	$3t_{CYCP}$+30	-	$3t_{CYCP}$+30	-	ns
SCK↓→SCS↑ hold time	t_{CSHE}		0	-	0	-	ns
SCS deselect time	t_{CSDE}		$3t_{CYCP}$+30	-	$3t_{CYCP}$+30	-	ns
SCS↓→SOT delay time	t_{DSE}		-	55	-	40	ns
SCS↑→SOT delay time	t_{DEE}		0	-	0	-	ns

*1: CSSU bit value × serial chip select timing operating clock cycle.

*2: CSHD bit value × serial chip select timing operating clock cycle.

*3: CSDS bit value × serial chip select timing operating clock cycle.
Irrespective of CSDS bit setting, $5t_{CYCP}$ or more are required for the period the time when the serial chip select pin becomes inactive to the time when the serial chip select pin becomes active again.

Notes:

- *t_{CYCP} indicates the APB bus clock cycle time.*
  For information about the APB bus number which Multi-function Serial is connected to, see "8. Block Diagram".
- *For information about CSSU, CSHD, CSDS, serial chip select timing operating clock, see "FM0+ Family Peripheral Manual".*
- *These characteristics only guarantee the same relocate port number.*
  For example, the combination of SCKx_0 and SCSIx_1 is not guaranteed.
- *When the external load capacitance C_L=30 pF.*

11.4.10 External Input Timing

(V_{CC}= 1.65 V to 3.6 V, V_{SS}= 0 V, T_A=- 40°C to +105°C)

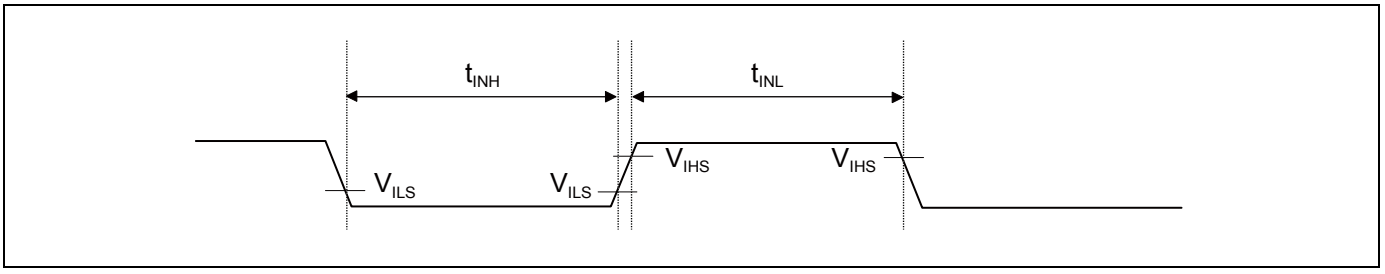
Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{INH}, t_{INL}	ADTGx	-	2 t_{CYCP}*1	-	ns	A/D converter trigger input
		INT00 to INT08, INT12, INT13, INT15, NMIX	*2	2 t_{CYCP} +100*1	-	ns	External interrupt, NMI
			*3	500	-	ns	
		WKUPx	*4	500	-	ns	Deep standby wake up

*1: t_{CYCP} represents the APB bus clock cycle time.
For the number of the APB bus to which the Multi-function Timer is connected and that of the APB bus to which the External Interrupt Controller is connected, see "8. Block Diagram".

*2: In Run mode and Sleep mode

*3: In Timer mode, RTC mode and Stop mode

*4: In Deep Standby RTC mode and Deep Standby Stop mode



11.5 12-bit A/D Converter

Electrical Characteristics of A/D Converter (Preliminary Values)

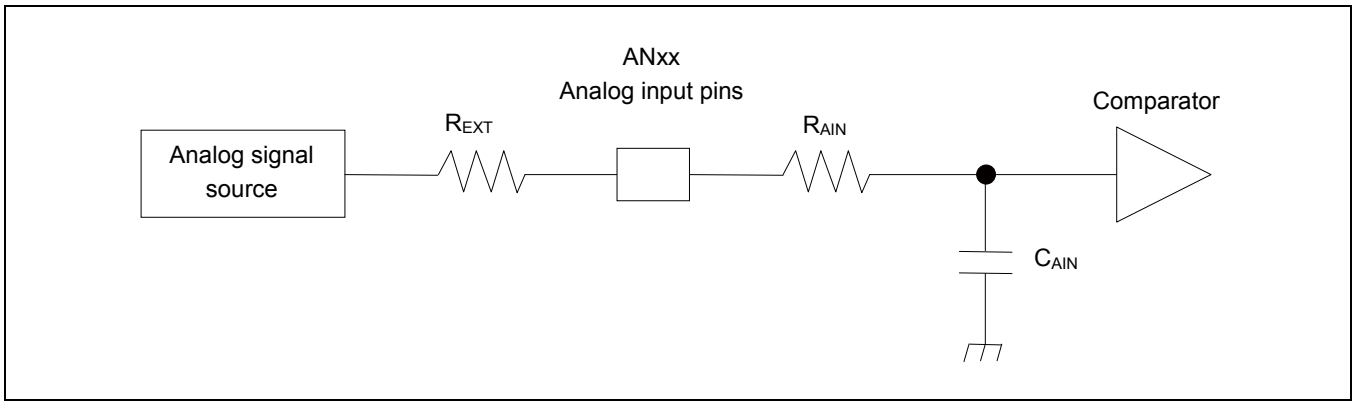
(V_{CC}= 1.65 V to 3.6 V, V_{SS}= 0 V, T_A=- 40°C to +105°C)

Parameter	Symbol	Pin Name	Value			Unit	Remarks
			Min	Typ	Max		
Resolution	-	-	-	-	12	bit	
Integral Nonlinearity	-	-	- 4.5	-	4.5	LSB	
Differential Nonlinearity	-	-	- 2.5	-	+ 2.5	LSB	
Zero transition voltage	V_{ZT}	ANxx	- 15	-	+ 15	mV	
Full-scale transition voltage	V_{FST}	ANxx	AVRH - 15	-	AVRH + 15	mV	
Conversion time*1	-	-	1.0	-	-	µs	$V_{CC} \geq 2.7$ V
			4.0	-	-		1.8 ≤ V_{CC} < 2.7 V
			10	-	-		1.65 ≤ V_{CC} < 1.8 V
Sampling time *2	Ts	-	0.3	-	10	µs	$V_{CC} \geq 2.7$ V
			1.2	-			1.8 ≤ V_{CC} < 2.7 V
			3.0	-			1.65 ≤ V_{CC} < 1.8 V
Compare clock cycle *3	Tcck	-	50	-	1000	ns	$V_{CC} \geq 2.7$ V
			200	-			1.8 ≤ V_{CC} < 2.7 V
			500	-			1.65 ≤ V_{CC} < 1.8 V
State transition time to operation permission	Tstt	-	-	-	1.0	µs	
Analog input capacity	C_{AIN}	-	-	-	7.5	pF	
Analog input resistance	R_{AIN}	-	-	-	2.2	kΩ	$V_{CC} \geq 2.7$ V
					5.5		1.8 ≤ V_{CC} < 2.7 V
					10.5		1.65 ≤ V_{CC} < 1.8 V
Interchannel disparity	-	-	-	-	4	LSB	
Analog port input leak current	-	ANxx	-	-	5	µA	
Analog input voltage	-	ANxx	V_{SS}	-	AVRH	V	
Reference voltage	-	AVRH	2.7	-	V_{CC}	V	VCC ≥ 2.7V
			V_{CC}				VCC < 2.7V
	-	AVRL	V_{SS}	-	V_{SS}	V	

*1: The conversion time is the value of sampling time (t_S) + compare time (t_C).
The minimum conversion time is computed according to the following conditions:
$V_{CC} \geq 2.7$ V sampling time=0.3 µs, compare time=0.7 µs
1.8 ≤ V_{CC} < 2.7 V sampling time=1.2 µs, compare time=2.8 µs
1.65 ≤ V_{CC} < 1.8 V sampling time=3.0 µs, compare time=7.0 µs
Ensure that the conversion time satisfies the specifications of the sampling time (t_S) and compare clock cycle (t_{CCK}).
For details of the settings of the sampling time and compare clock cycle, refer to "Chapter: A/D Converter" in "FM0+ Family Peripheral Manual Analog Macro Part".
The register settings of the A/D Converter are reflected in the operation according to the APB bus clock timing.
For the number of the APB bus to which the A/D Converter is connected, see "8. Block Diagram".
The base clock (HCLK) is used to generate the sampling time and the compare clock cycle.

*2: The required sampling time varies according to the external impedance.
Set a sampling time that satisfies (Equation 1).

*3: The compare time (t_C) is the result of (Equation 2).



(Equation 1) $t_S \geq (R_{AIN} + R_{EXT}) \times C_{AIN} \times 9$

t_S: Sampling time

R_{AIN}: Input resistance of A/D Converter = 2.2 kΩ with 2.7 ≤ VCC ≤ 3.6
Input resistance of A/D Converter = 5.5 kΩ with 1.8 ≤ VCC ≤ 2.7
Input resistance of A/D Converter = 10.5 kΩ with 1.65 ≤ VCC ≤ 1.8

C_{AIN}: Input capacitance of A/D Converter = 7.5 pF with 1.65 ≤ VCC ≤ 3.6

R_{EXT}: Output impedance of external circuit

(Equation 2) $t_C = t_{CCK} \times 14$

t_C: Compare time

t_{CCK} : Compare clock cycle

12. Ordering Information

Part number	On-chip Flash memory [Kbyte]	On-Chip SRAM [Kbyte]	Package	Packing
S6E1C12D0AGV20000	128	16	Plastic • LQFP (0.50 mm pitch), 64 pins (FPT-64P-M38)	Tray
S6E1C11D0AGV20000	64	12		
S6E1C12C0AGV20000	128	16	Plastic • LQFP (0.50 mm pitch), 48 pins (FPT-48P-M49)	Tray
S6E1C11C0AGV20000	64	12		
S6E1C12B0AGP20000	128	16	Plastic • LQFP (0.80 mm pitch), 32 pins (FPT-32P-M30)	Tray
S6E1C11B0AGP20000	64	12		
S6E1C12D0AGN20000	128	16	Plastic • QFN64 (0.50 mm pitch), 64 pins (LCC-64P-M25)	Tray
S6E1C11D0AGN20000	64	12		
S6E1C12C0AGN20000	128	16	Plastic • QFN48 (0.50 mm pitch), 48 pins (LCC-48P-M74)	Tray
S6E1C11C0AGN20000	64	12		
S6E1C12B0AGN20000	128	16	Plastic • QFN32 (0.50 mm pitch), 32 pins (LCC-32P-M73)	Tray
S6E1C11B0AGN20000	64	12		

Document History

Document Title: S6E1C1 Series 32-bit ARM® Cortex®-M0+ FM0+ Microcontroller
Document Number: 002-00234

Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	4896074	TEKA	08/31/2015	New Spec.
*A	4955136	TEKA	10/9/2015	AC/DC characteristics updated. Typo fixed in “List of Pin Functions”.